Listing of Claims:

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- 1. (Currently Amended) A microdissection apparatus to obtain a necessary area from a sample, comprising:
 - a laser light source to emit laser light; and
- a laser light irradiation optical system to irradiate the sample with the laser light from the laser light source; [[,]]

wherein the laser light irradiation optical system including comprises an active optical element [[,]] which is allowed to form forms thereon a pattern reflecting corresponding to the necessary area, and the laser light irradiation optical system setting sets a laser light irradiation area, to in which the laser light is applied on the sample, based on via the pattern formed on the active optical element.

- 2. (Original) The microdissection apparatus according to claim 1, further comprising a pattern image projection optical system, which projects an image of the pattern formed on the active optical element onto the sample.
- 3. (Original) The microdissection apparatus according to claim 2, further comprising an observation optical system, which acquires an observation image of the sample.

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- 4. (Currently Amended) The microdissection apparatus according to claim 3, further comprising <u>a</u> display unit to display the observation image acquired by the observation optical system, and <u>an</u> input unit to input information for setting the pattern formed on the active optical element.
- 5. (Currently Amended) The microdissection apparatus according to claim 3, further comprising <u>a</u> control unit to set the pattern formed on the active optical element based on the observation image acquired by the observation optical system.
- 6. (Currently Amended) The microdissection apparatus according to claim 1, wherein the laser light irradiation optical system selectively irradiates the a part of the sample that surrounds the necessary area with the laser light in accordance with the pattern formed on the active optical element, and the laser light applied to the sample has an energy density sufficient for evaporating the sample, and such that the part of the sample irradiated with the laser light is evaporated so that as to cut the necessary area is cut from the sample.
- 7. (Currently Amended) The microdissection apparatus according to claim 1, wherein the laser light irradiation optical system includes further comprises an objective lens arranged

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close to the sample, a relay lens to be appropriately arranged on which is removably inserted into an optical path between the active optical element and the objective lens, and a relay lens attachment/detachment insertion/removal mechanism to attach/detach insert and remove the relay lens to/from into and from the optical path; [[,]]

in a state that wherein when the relay lens is positioned on inserted in the optical path, the active optical element forms the pattern reflecting corresponding to the necessary area, and the laser light irradiation optical system selectively irradiates a part of the sample excluding the necessary area with the laser light in accordance with the pattern formed on the active optical element; [[,]] and

in a state that wherein when the relay lens is off removed from the optical path, the laser light irradiation optical system converges the a beam of laser light by the objective lens to irradiate the sample with the converged beam.

8. (Currently Amended) The microdissection apparatus according to claim 7, wherein, in the state that when the relay lens is off removed from the optical path, the converged beam of laser light, which is converged by the objective lens to illuminate the sample, has an energy density sufficient for evaporating the sample.

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9. (Currently Amended) The microdissection apparatus according to claim 8, further comprising <u>a</u> movement mechanism, which relatively moves <u>the sample and</u> a beam spot of the <u>converged beam of laser light formed on the sample; and the sample</u>,

wherein the beam spot of the laser light is relatively moved on the sample by the movement mechanism to surround completely around an area to be collected including the necessary area, and a part of the sample irradiated with the converged beam of laser light is evaporated to be cut, so such that the area to be collected including the necessary area is cut from the sample.

- 10. (Original) The microdissection apparatus according to claim 1, wherein the active optical element comprises a transmission type active optical element.
- 11. (Original) The microdissection apparatus according to claim 1, wherein the active optical element comprises a reflection type active optical element.
- 12. (Currently Amended) A microdissection apparatus to obtain a necessary area from a sample, comprising:
 - a light source means for emitting laser light; and

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a laser light irradiation optical system to irradiate the sample with the laser light from the light source means; [[,]]

wherein the laser light irradiation optical system including comprises pattern forming means for forming a pattern reflecting corresponding to the necessary area, and the laser light irradiation optical system setting sets a laser light irradiation area, to in which the laser light is applied on the sample, based on via the pattern formed by the pattern forming means.

- 13. (Original) The microdissection apparatus according to claim 12, further comprising a pattern image projection optical system for projecting an image of the pattern formed by the pattern forming means onto the sample.
- 14. (Original) The microdissection apparatus according to claim 13, further comprising an observation optical system for acquiring an observation image of the sample.
- 15. (Original) The microdissection apparatus according to claim 14, further comprising displaying means for displaying the observation image acquired by the observation optical system, and inputting means for inputting information for setting the pattern formed by the pattern forming means.

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- 16. (Currently Amended) The microdissection apparatus according to claim 14, further comprising <u>a</u> controller for setting the pattern formed by the pattern forming means based on the observation image acquired by the observation optical system.
- 17. (Currently Amended) The microdissection apparatus according to claim 12, wherein the laser light irradiation optical system selectively irradiates the a part of the sample that surrounds the necessary area with the laser light in accordance with the pattern formed by the pattern forming means, and the laser light applied to the sample has an energy density sufficient for evaporating the sample, and such that the part of the sample irradiated with the laser light is evaporated so that as to cut the necessary area is cut from the sample.
- 18. (Currently Amended) The microdissection apparatus according to claim 1, wherein the laser light irradiation optical system includes further comprises an objective lens arranged close to the sample, a relay lens, which is appropriately arranged on removably inserted into an optical path between the pattern forming means and the objective lens, and a relay lens attachment/detachment insertion/removal mechanism, which attaches/detaches inserts and removes the relay lens to/from into and from the optical path; [[,]]

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in a state that wherein when the relay lens is positioned on inserted in the optical path, the pattern forming means forms the pattern reflecting corresponding to the necessary area, and the laser light irradiation optical system selectively irradiates a part of the sample excluding the necessary area with the laser light in accordance with the pattern formed on the pattern forming means; [[,]] and

in a state that wherein when the relay lens is off removed from the optical path, the laser light irradiation optical system converges the a beam of laser light by the objective lens to irradiate the sample with the converged beam.

- 19. (Currently Amended) The microdissection apparatus according to claim 18, wherein, in the state that when the relay lens is off removed from the optical path, the converged beam of laser light, which is converged by the objective lens to illuminate the sample, has an energy density sufficient for evaporating the sample.
- 20. (Currently Amended) The microdissection apparatus according to claim 19, further comprising moving means for relatively moving the sample and a beam spot of the converged beam of laser light formed on the sample; and the sample,

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including the necessary area is cut from the sample.

- 21. (Original) The microdissection apparatus according to claim 12, wherein the pattern forming means comprises a transmission type active optical element.
- 22. (Original) The microdissection apparatus according to claim 12, wherein the pattern forming means comprises a reflection type active optical element.
- 23. (Currently Amended) A microdissection method for obtaining a necessary area from a sample, comprising:

irradiating the sample with laser light through an active optical element, which is allowed to form forms thereon a pattern reflecting corresponding to the necessary area.

24. (Currently Amended) The microdissection method according to claim 23, wherein a part of the sample which surrounds the necessary area is selectively irradiated with the

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laser light in accordance with the pattern formed on the active optical element and it is evaporated, thereby cutting the necessary area from the sample.

25. (Currently Amended) The microdissection method according to claim 24, wherein further comprising:

projecting an image of the pattern formed on the active
optical element is projected onto the sample; [[,]]

obtaining an observation image of the sample; is obtained,
and

- a setting the pattern formed on the active optical element is set based on the obtained observation image.
- 26. (Currently Amended) The microdissection apparatus according to claim 23, wherein a part of the sample excluding the necessary area is selectively irradiated with the laser light in accordance with the pattern formed on the active optical element, and the selective irradiation of the laser light is repeatedly performed while changing positions on the sample that are irradiated to irradiate all desired positions on the sample; according to needs, and

wherein the method further comprises converging a beam of the irradiated laser light onto a beam spot of the laser light formed on the sample; and is

beam of laser light with respect to the sample while converged beam of laser light and irradiating the sample with the converged beam to surround the completely around an area to be collected including the necessary area; 7 the

wherein a part of the sample irradiated with the converged beam of laser light is evaporated, and such that the area to be collected including the necessary area is cut from the sample.

- 27. (New) The microdissection apparatus according to claim 1, further comprising an observation optical system, which acquires an observation image of the sample.
- 28. (New) The microdissection apparatus according to claim 27, wherein the observation optical system comprises an erecting microscope.
- 29. (New) The microdissection apparatus according to claim 27, wherein the observation optical system comprises an inverted microscope.
- 30. (New) The microdissection apparatus according to claim 3, wherein the laser light irradiation optical system and the observation optical system have an objective lens in common.

- 31. (New) The microdissection apparatus according to claim 27, wherein the laser light irradiation optical system and the observation optical system have an objective lens in common.
- 32. (New) The microdissection apparatus according to claim 3, wherein the observation optical system comprises an erecting microscope.
- 33. (New) The microdissection apparatus according to claim 3, wherein the observation optical system comprises an inverted microscope.
- 34. (New) The microdissection apparatus according to claim 10, wherein the transmission type active optical element comprises a liquid crystal substrate.
- 35. (New) The microdissection apparatus according to claim 11, wherein the reflection type active optical element comprises a micro mirror array.
- 36. (New) The microdissection apparatus according to claim 1, wherein the laser light irradiation optical system selectively irradiates a part of the sample that surrounds the necessary area with the laser light in accordance with the

pattern formed on the active optical element, the laser light applied to the sample is relatively moved on the sample by a movement mechanism completely around an area to be collected including the necessary area, and a part of the sample irradiated with the converged beam of laser light is evaporated to be cut, such that the area to be collected including the necessary area is cut from the sample.